



#### **DUAL 2-INPUT NAND GATE WITH OPEN-DRAIN OUTPUTS**

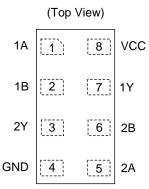
#### **Description**

The 74LVC2G38 is a dual, two input NAND gate with open-drain outputs. Both gates have open-drain outputs designed for operation over a power supply range of 1.65V to 5.5V. The device is fully specified for partial power down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output preventing damaging current backflow when the device is powered down. Each gate performs the positive Boolean function

$$Y = \overline{A \bullet B}$$
 or  $Y = \overline{A} + \overline{B}$ 

It is understood that the logical HIGH output level is a result of pullup resistor.

#### **Pin Assignments**



X2-DFN2010-8 X2-DFN1410-8 X2-DFN1210-8

#### **Features**

- Wide Supply Voltage Range from 1.65V to 5.5V
- Outputs Sink 24mA at Vcc = 3.3V
- CMOS Low Power Consumption
- I<sub>OFF</sub> Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- Schmitt Trigger Action at all inputs makes the circuit tolerant for slower input rise and fall times. The hysteresis is typically 100mV at V<sub>CC</sub> = 3.0V
- ESD Protection Exceeds JESD 22
  - 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Applications**

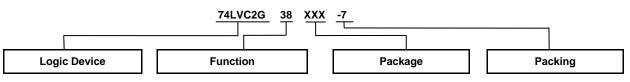
- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
  - PCs, Networking, Notebooks, Netbooks, PDAs
  - Tablet Computers, E-readers
  - Computer Peripherals, Hard Drives, CD/DVD ROMs
  - TVs, DVDs, DVRs, Set Top Boxes
  - Cell Phones, Personal Navigation / GPS
  - MP3 Players, Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



#### **Ordering Information** (Note 4)



74: Logic Prefix LVC: 1.65V to 5.5V Logic Family 2G: Dual Gate

38: 2-Input NAND Gate With Open-Drain Outputs HD4: X2-DFN2010-8 HK3: X2-DFN1410-8 RA3: X2-DFN1210-8 -7: 7" Tape & Reel

	Package Package		Package	7" Tape and Reel (Note 6)		
Device	Code	(Note 5)	Size	Quantity	Part Number Suffix	
74LVC2G38HD4-7	HD4	X2-DFN2010-8	1.95mm x 1.0mm x 0.4mm 0.5mm lead pitch	5,000/Tape & Reel	-7	
74LVC2G38HK3-7	HK3	X2-DFN1410-8	1.35mm x 1.0mm x 0.35mm 0.4mm lead pitch	5,000/Tape & Reel	-7	
74LVC2G38RA3-7	RA3	X2-DFN1210-8	1.2mm x 1.0mm x 0.35mm 0.3mm lead pitch	5,000/Tape & Reel	-7	

Notes: 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

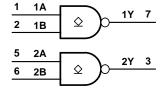
- 5. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/packageoutlines.html.

  6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Pin Descriptions**

Pin Name	Pin No.	Description	
1A	1	Data Input	
1B	2	Data Input	
2Y	3	Data Output (Open Drain)	
GND	4	Ground	
2A	5	Data Input	
2B	6	Data Input	
1Y	7	Data Output (Open Drain)	
V <sub>CC</sub>	8	Supply Voltage	

## **Logic Diagram**



## **Function Table**

Inp	Output	
Α	Υ	
L	L	Z
L	Н	Z
Н	L	Z
Н	Н	L



## Absolute Maximum Ratings (Notes 7 & 8)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
Vcc	Supply Voltage	-0.5 to +6.5	V
VI	Input Voltage	-0.5 to +6.5	V
Vo	Output Voltage -Active Mode	-0.5 to +6.5	V
Vo	Output Voltage Power Down Mode	-0.5 to +6.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current (Vo < 0)	-50	mA
lo	Continuous Output Current (Vo = 0 to 5.5V)	50	mA
Icc	Continuous Current Through V <sub>CC</sub>	100	mA
I <sub>GND</sub>	Continuous Current Through GND	-100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Notes:

# **Recommended Operating Conditions** (Note 9)

Symbol	Pa	arameter	Min	Max	Unit
.,	Operation Voltage	Operating	1.65	5.5	V
Vcc	Operating Voltage	Data Retention Only	1.5	_	V
VI	Input Voltage	•	0	5.5	V
.,	Output Voltage Active Mode		0	5.5	V
Vo	Output Voltage Power-Down Mode		0	5.5	V
		V <sub>CC</sub> = 1.65V	_	4	
		V <sub>CC</sub> = 2.3V	_	8	
la.	Low-Level Output Current	V <sub>CC</sub> = 2.7V	_	12	mA
loL	Low-Level Output Current	V 2.0V	_	16	IIIA
		$V_{CC} = 3.0V$	_	24	
		V <sub>CC</sub> = 4.5V	_	32	
Δt/ΔV	Input Transition Disc or Fall Data	V <sub>CC</sub> = 1.65V to 2.7V	_	20	/\/
ΔυΔν	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 2.7V to 5.5V	_	10	ns/V
TA	Operating Free-Air Temperature		-40	+125	°C

Note: 9. Unused inputs should be held at  $V_{CC}$  or Ground.

<sup>7.</sup> Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

<sup>8.</sup> Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.



# Electrical Characteristics (All typical values are at T<sub>A</sub> = +25°C)

		T 10 111	.,	-40	°C to +8	5°C	-40°C to	+125°C	1114		
Symbol	Parameter	Test Conditions	V <sub>cc</sub>	Min	Тур.	Max	Min	Max	Unit		
			$V_{CC} = 1.65V \text{ to } 1.95V$	0.65 x V <sub>CC</sub>		_	0.65 x V <sub>CC</sub>	_			
.,	High-Level		V <sub>CC</sub> = 2.3V to 2.7V	1.7	-	_	1.7	_	1		
$V_{IH}$	Input Voltage	_	V <sub>CC</sub> = 2.7V to 3.6V	2.0	_	_	2.0	_	V		
			$V_{CC} = 4.5V \text{ to } 5.5V$	0.7 x V <sub>CC</sub>	_	_	0.7 x V <sub>CC</sub>	_			
			$V_{CC} = 1.65V \text{ to } 1.95V$	_		0.35 x V <sub>CC</sub>	1	0.35 x V <sub>CC</sub>			
V	Low-Level		$V_{CC} = 2.3V \text{ to } 2.7V$	_		0.7	1	0.7	V		
$V_{IL}$	Input Voltage	_	$V_{CC} = 2.7V \text{ to } 3.6V$	_	ı	0.8	1	0.8	V		
			$V_{CC} = 4.5V \text{ to } 5.5V$	_		0.3 x V <sub>CC</sub>	1	0.3 x V <sub>CC</sub>			
		$I_{OL} = 100 \mu A$	1.65V to 5.5V	_	0	0.1	_	0.1			
				$I_{OL} = 4mA$	1.65V	_	0.08	0.45	_	0.7	
	Low-Level	$I_{OL} = 8mA$	2.3V	_	0.14	0.3	_	0.45			
$V_{OL}$	Output	$I_{OL} = 12mA$	2.7V	_	0.19	0.4	_	0.6	V		
	Voltage I <sub>OL</sub> = 16mA	$I_{OL} = 16mA$	3V	_	0.25	0.4	_	0.6			
		$I_{OL} = 24mA$	30	_	0.37	0.55	_	0.8			
		$I_{OL} = 32mA$	4.5V	_	0.43	0.55	1	0.8			
lı	Input Current	V <sub>I</sub> = 5.5V or GND	0V to 5.5V	_	± 0.1	±5	_	± 20	μA		
l <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 = 5.5V$	0V	_	± 0.1	±10	_	±20	μА		
Icc	Supply Current	$V_I = 5.5V$ or GND $I_O = 0A$	1.65V to 5.5V	_	0.1	10	-	40	μA		
ΔI <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> – 0.6V Other inputs at V <sub>CC</sub> or GND	2.3V to 5.5V	_	5	500	_	5,000	μА		
Cı	Input Capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3V	_	2.5	_	_	_	pF		



## **Operating Characteristics**

Parameter		Test Conditions	V <sub>cc</sub> = 1.8V Typ.	V <sub>CC</sub> = 2.5V Typ.	V <sub>CC</sub> = 3.3V Typ.	V <sub>cc</sub> = 5V Typ.	Unit
$C_{pd}$	Power Dissipation Capacitance	f = 10MHz	6	7	7	9	pF

# **Package Characteristics**

Symbol	Parameter	Package	Test Conditions	Min	Тур.	Max	Unit
	- 15	X2-DFN2010-8		_	313	_	
$\theta_{JA}$	Thermal Resistance Junction- to-Ambient	X2-DFN1410-8	(Note 10)	_	321	_	°C/W
	to-Ambient	X2-DFN1210-8		_	395	_	
	- 15	X2-DFN2010-8		_	145	_	
$\theta_{JC}$	Thermal Resistance Junction-	X2-DFN1410-8	(Note 10)	_	166	_	°C/W
	to-Case	X2-DFN1210-8		_	236	_	

Note: 10. Test condition for each package type: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

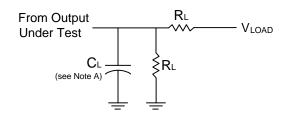
# **Switching Characteristics**

Typical Values at  $T_A = +25$ °C and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V. See Figure 1.

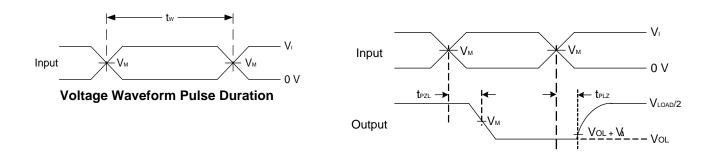
B	From	То	V	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$			T <sub>A</sub> = -40°C	to +125°C	1111
Parameter	Input	Output	V <sub>CC</sub>	Min	Тур	Max	Min	Max	Unit
			1.8V ± 0.15V	1.2	3.0	8.6	1.2	10.8	
			2.5V ± 0.2V	0.7	1.8	4.8	0.7	6.0	
t <sub>PZL</sub>	A or B	Υ	2.7V	0.7	2.5	4.4	0.7	5.5	ns
			$3.3V \pm 0.3V$	0.7	2.1	4.1	0.7	5.2	
			5.0V ± 0.5V	0.5	1.5	3.3	0.5	4.2	
			1.8V ± 0.15V	1.2	3.0	8.6	1.2	10.8	
			2.5V ± 0.2V	0.7	1.8	4.8	0.7	6.0	
t <sub>PLZ</sub> A or B	3 Y	2.7V	0.7	2.5	4.4	0.7	5.5	ns	
			$3.3V \pm 0.3V$	0.7	2.1	4.1	0.7	5.2	
			5.0V ± 0.5V	0.5	1.5	3.3	0.5	4.2	



#### **Parameter Measurement Information**



V	Inp	outs	V	V			V.
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	RL	<b>V</b> Δ
1.8V ± 0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	1kΩ	0.15V
2.5V ± 0.2V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V ± 0.3V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5.0V ± 0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	50pF	500Ω	0.3V



**Voltage Waveforms Inverting and Non Inverting Outputs** 

Figure 1. Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10MHz.

C. Inputs are measured separately one transition per measurement.



## **Marking Information**

(Top View)

<u>XX</u> 

XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week

X: Internal Code

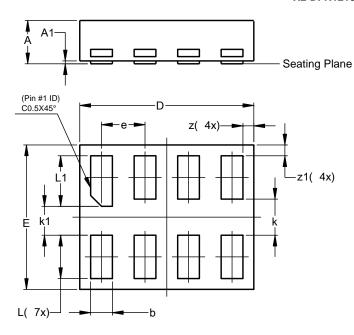
Part Number	Package	Identification Code
74LVC2G38HD4-7	X2-DFN2010-8	9M
74LVC2G38HK3-7	X2-DFN1410-8	9N
74LVC2G38RA3-7	X2-DFN1210-8	9P



# X2-DFN1210-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1210-8

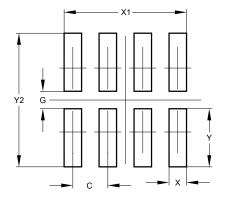


	X2-DFN	N1210-8						
Dim	Min	Max	Тур					
Α	-	0.35	0.30					
A1	0	0.03	0.02					
b	0.10	0.20	0.15					
D	1.15	1.25	1.20					
Е	0.95	1.05	1.00					
е	-	-	0.30					
k	-	-	0.25					
k1	-	-	0.20					
L	0.25	0.35	0.30					
L1	0.30	0.40	0.35					
Z	0.050	0.100	0.075					
<b>z</b> 1	0.050	0.100	0.075					
All I	All Dimensions in mm							

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1210-8



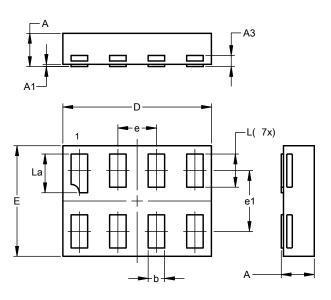
Dimensions	Value (in mm)
С	0.300
G	0.150
Х	0.150
X1	1.050
Υ	0.500
V1	1 150



# X2-DFN1410-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1410-8

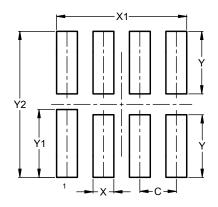


X2-DFN1410-8				
Dim	Min	Max	Тур	
Α	0.30	0.35	0.33	
A1	0.00	0.03	0.02	
А3			0.10	
b	0.12	0.20	0.15	
D	1.30	1.40	1.35	
E	0.95	1.05	1.00	
е			0.35	
e1			0.55	
L	0.27	0.35	0.30	
L1	0.32	0.40	0.35	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1410-8



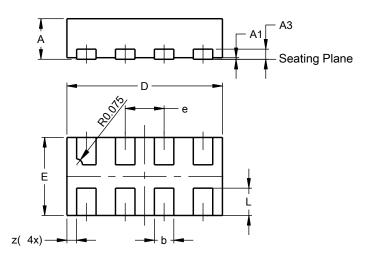
Dimensions	Value (in mm)	
С	0.350	
Х	0.200	
X1	1.250	
Y	0.600	
Y1	0.650	
Y2	1.400	



# X2-DFN2010-8 Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN2010-8

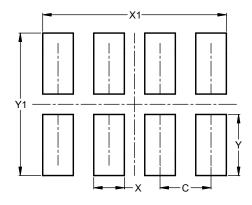


X2-DFN2010-8				
Dim	Min	Max	Тур	
Α		0.40		
A1	0.00	0.05	0.02	
А3			0.13	
b	0.20	0.30	0.25	
D	1.950	2.05	2.00	
Е	0.95	1.05	1.00	
е			0.50	
L	0.30	0.40	0.35	
Z			0.125	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN2010-8



Dimensions	Value (in mm)
С	0.500
X	0.300
X1	1.800
Υ	0.600
Y1	1 400



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